

DFN1006-2 Plastic-Encapsulate Schottky Barrier Diode

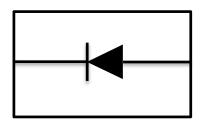
Description

General application schottky barrier diode, encapsulated in a DFN1006-2 leadless ultra small Surface-Mounted Device (SMD) plastic package.

Features

- Forward current: 1 A
- Reverse voltage: V_R ≥ 40 V
- Low forward voltage: $V_F \leq 0.6 V @1A$
- Low reverse current: $I_R \leq 100~\mu$ A @ 40 V
- High reliability

Schematic and Pin Configuration



Graphic symbol

Package



DFN1006-2(Bottom View)

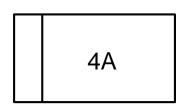
Mechanical Characteristics

- DFN1006-2 Small Outline Plastic Package
- Level 1 moisture sensitivity per J-STD-020
- Case Material: "Green" Molding Compound
- We declare that the material of product compliance with RoHS requirements and Halogen Free

Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch Mode Power Supply (SMPS)
- Low power consumption applications
- Ultra high-speed switching
- LED backlight for mobile application

Marking Information



4A = Device Marking Code Bar denotes Cathode

Ordering Information

Part Number	Shipping	Reel Size
PSB40V1P1	10000/Tape & Reel	7 inch



Maximum Ratings (TA=25°C unless otherwise specified)

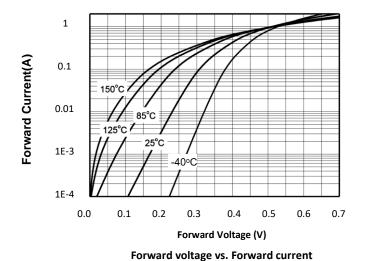
Parameter	Symbol	Value	Unit
DC Reverse Voltage	V _R	40	V
Mean Rectifying Current	lo 1		А
Non-repetitive Peak Forward Surge Current @ t=8.3ms	I _{FSM} 5		А
Power Dissipation	P _D	400	mW
Thermal Resistance from Junction to Ambient	R _{0JA}	310	°C/W
Junction Temperature	TJ	150	°C
Operating Temperature	Тор	-40 ~ +85	°C
Storage Temperature	T _{STG}	-40 ~ +125	°C

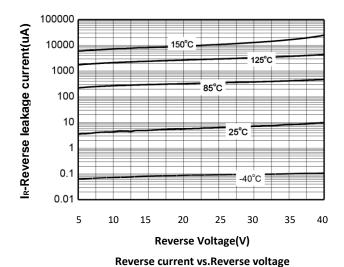
Electrical Characteristics (TA=25°C unless otherwise specified)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Test Condition
Forward Voltage	VF	ı	ı	0.40	٧	I _F =0.1A
		-	-	0.60	V	I _F =1A
Reverse Current	I _R	-	-	100	μA	V _R = 40V



Typical Performance Characteristics(T_A=25°C unless otherwise specified)

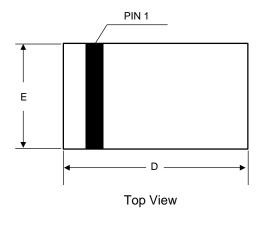


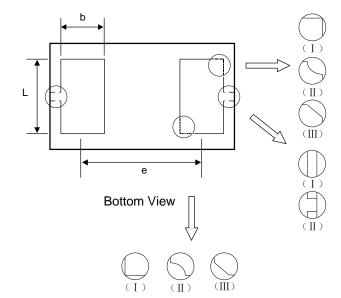


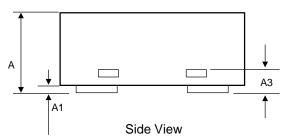
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DFN1006-2 Package Outline Drawing

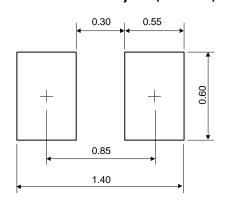






Symbol	Dimensions in Millimeters			
	Min.	Тур.	Max.	
А	0.340	0.450	0.550	
A1	0.000	0.050		
A3	0.125 Ref.			
D	0.950	1.000	1.075	
E	0.490	0.600	0.675	
b	0.200	0.250	0.300	
L	0.450	0.500	0.550	
е	0.650 BSC			

Recommended PCB Layout (Unit: mm)



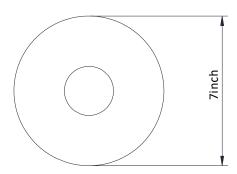
Notes:

This recommended land pattern is for reference purposes only. Please consult your manufacturing group to ensure your PCB design guidelines are met.

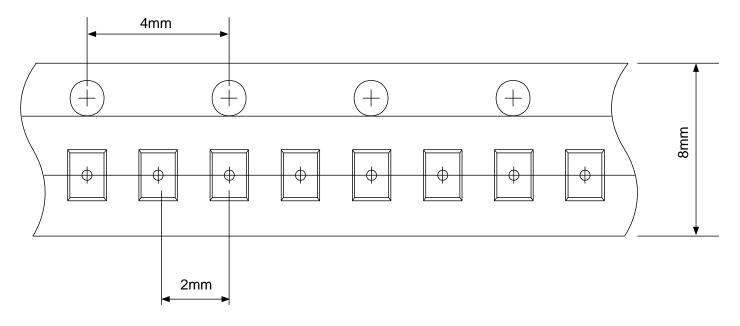


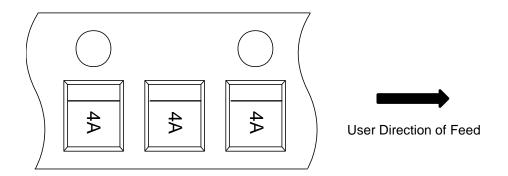
TAPE AND REEL INFORMATION





Tape Dimensions







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